Special Issue

Millimeter-Wave and THz Integrated Technologies and Applications

Message from the Guest Editor

The aggressive downscaling of CMOS and III-V semiconductor technologies opens up new perspectives for the development of circuits and systems operating at millimeter-wave and THz frequencies. This concerns a wide range of applications including medical applications and sensing. However, the development of highly miniaturized and complete THz systems still poses major challenges, some of which are related to the accessibility of accurate device models, the development of suitable packaging technologies and the availability of established, accurate, on- and off-wafer characterization tools and methodologies. This Special Issue will publish high-quality, original research papers on the following topics: Semiconductor CMOS and III-V technologies, substrates and devices for mmWave and THz circuits; State-of-the-art integrated mmWave and THz active and passive circuits and systems; Packaging and interposer technologies for compact mmWave and THz system development; On- and off-wafer tools and methodologies for accurate and efficient mmWave and THz technologies, circuits and system characterization.

Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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